Special Issue

Electronic Packaging Technologies and Applications

Message from the Guest Editors

With the rapid development of wide bandgap semiconductors, 5G communication technology, etc., electronic packaging technology as a bridge connecting electronic devices and systems, especially for high-temperature, high-voltage, and high-frequency applications, has become increasingly important. In order to discuss in depth the latest progress, challenges, and opportunities of electronic packaging technology, as well as its application in various fields, we hereby invite high-quality manuscripts to be submitted to this Special Issue on “Electronic Packaging Technologies and Applications”. This Special Issue aims to focus on the recent developments in advanced power electronics packaging technology and novel applications thereof. This includes (but is not limited to) advanced packaging technologies, packaging materials and processes, die attach and interconnection technologies, innovative packaging strategies, wide-bandgap device packaging, packaging design and modelling, system integration and optimization, thermal management, reliability assessment and lifetime prediction, application analysis, etc.

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About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

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